

Silicon Carbide (SiC) **Schottky Diode** - EliteSiC, 50 A, 1200 V, D3, TO-247-2L

NDSH50120C-F155

Description

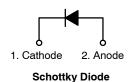
Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 380 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery / No Forward Recovery
- This Device is Halide Free and RoHS Compliant with exemption 7a, Pb-Free 2LI (on second level interconnection)

Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits





MARKING DIAGRAM



DSH50120C

YWW

77

1

= Specific Device Code

= Assembly Plant Code

= Date Code (Year & Week)

= Lot Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS ($T_J = 25$ °C unless otherwise noted)

Symbol	Parameter		Value	Unit
V_{RRM}	Peak Repetitive Reverse Voltage		1200	V
E _{AS}	Single Pulse Avalanche Energy (Note 1)		380	mJ
I _F	I _F Continuous Rectified Forward Current @ T _C < 139°C Continuous Rectified Forward Current @ T _C < 135°C		50	А
			53	
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	1568	А
		T _C = 150°C, 10 μs	1414	Α
I _{F,SM}	Non-Repetitive Forward Surge Current	Half-Sine Pulse, t _p = 8.3 ms	231	Α
I _{F,RM}	Repetitive Forward Surge Current	Half-Sine Pulse, t _p = 8.3 ms	84	Α
Ptot	Ptot Power Dissipation	T _C = 25°C	375	W
		T _C = 150°C	62.5	W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. E_{AS} of 380 mJ is based on starting T_J = 25°C, L = 0.5 mH, I_{AS} = 39 A, V = 50 V.

THERMAL CHARACTERISTICS

Symbol	Symbol Parameter		Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max	0.4	°C/W
$R_{\theta JA}$	R _{0JA} Thermal Resistance, Junction to Ambient, Max		°C/W

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

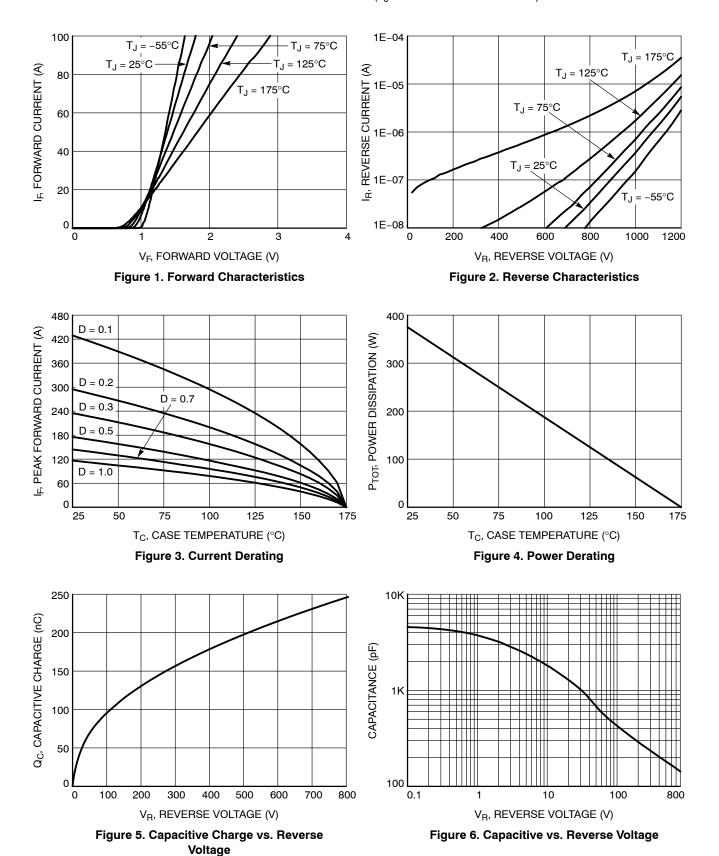
Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V _F	Forward Voltage	I _F = 50 A, T _J = 25°C	-	1.4	1.75	V
		I _F = 50 A, T _J = 125°C	-	1.63	-	
		I _F = 50 A, T _J = 175°C	-	1.84	-	
I _R	Reverse Current	V _R = 1200 V, T _J = 25°C	-	12.2	200	μΑ
		V _R = 1200 V, T _J = 125°C	-	30	200	
		V _R = 1200 V, T _J = 175°C	-	61.5	200	
Q _C	Total Capacitive Charge	V = 800 V	-	246	-	nC
С	Total Capacitance	V _R = 1 V, f = 100 kHz	-	3691	-	pF
		V _R = 400 V, f = 100 kHz	-	198	-	
		V _R = 800 V, f = 100 kHz	_	143	_	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Part Number	Top Marking	Package	Shipping
NDSH50120C-F155	DSH50120C	TO-247-2LD (Pb-Free / Halogen Free)	30 Units / Tube

TYPICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)



TYPICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

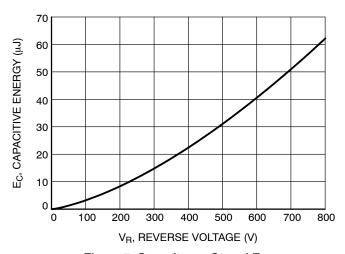


Figure 7. Capacitance Stored Energy

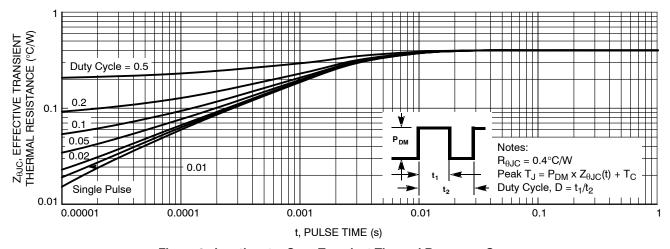
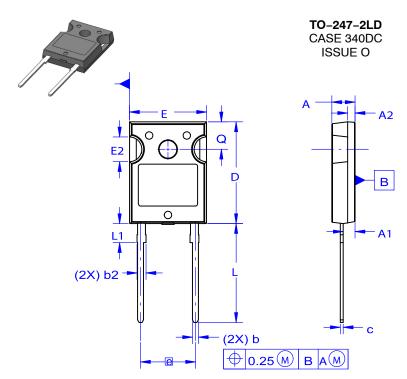
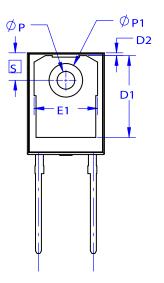


Figure 8. Junction-to-Case Transient Thermal Response Curve

PACKAGE DIMENSIONS





MILLIMITERS

NOTES:

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

DIM	MIN	NOM	MAX
Α	4.58	4.70	4.82
A1	2.20	2.40	2.60
A2	1.40	1.50	1.60
b	1.17	1.26	1.35
b2	1.60	1.72	1.84
С	0.51	0.61	0.71
D	20.32	20.57	20.82
D1	13.08	~	~
D2	0.51	0.93	1.35
Е	15.37	15.62	15.87
E1	12.81	~	~
E2	4.96	5.08	5.20
е	~	11.12	~
L	19.75	20.00	20.25
L1	3.69	3.81	3.93
ØР	3.51	3.58	3.65
Ø P1	6.60	6.80	7.00
Q	5.34	5.46	5.58
S	5.34	5.46	5.58

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code A = Assembly Location

Y = Year WW = Work Week

ZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.

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